# CRYSTAL OSCILLATOR (Programmable) SPREAD SPECTRUM

**OUTPUT: CMOS** 

**SG-9101** series

• Frequency range : 0.67 MHz ~ 170 MHz (1 ppm Step)

• Supply voltage : 1.62 V ~ 3.63 V

• Function : Output enable (OE) or Standby (ST)

• Down or Center spread modulation

· Configurable spreading

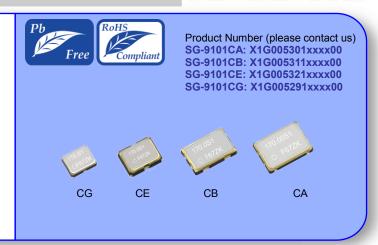
3 modulation profile (Hershey-kiss, Sine-wave, Triangle),

4 modulation frequency, 6 spread percentage

• Package : 2.5 x 2.0, 3.2 x 2.5, 5.0 x 3.2, 7.0 x 5.0 (mm)

• PLL technology to enable short lead time

Available field oscillator programmer "SG-Writer II"



### Specifications (characteristics)

Item Sym		Symbol			ications	Condition	ons/Remarks		
Supply voltage		Vcc	1.80 V Typ. 2.50 V Typ. 3.30 V Typ.			_	_		
Supply voltage		VCC	1.62 V ~ 1.98 V	1.98 V ~ 2.20 V	2.20 V ~ 2.80 V	2.70 V ~ 3.63 V	<u> </u>		
Output frequence	cy range	fo		0.67 MHz	~ 170 MHz				
Storage temper	ature	T_stg			+125 °C		Storage as single product.		
Operating temperature T_use				~ +85 °C					
		f tol			× 10 <sup>-6</sup>		Average frequency of 1s gate time.		
Frequency toler	ance	1_101	3.4 mA Max.	3.5 mA Max.	3.6 mA Max.	3.7 mA Max.	T use = +105 °C	gate time.	
			2.9 m		3.0 mA Typ.	3.7 mA wax. 3.2 mA Typ.	T use = +25 °C	o load, f <sub>O</sub> = 20 MHz	
Current consum	nption	Icc	5.7 mA Max.	6.0 mA Max.	6.9 mA Max.	8.3 mA Max.	T_use = +105 °C		
			4.9 m		5.9 mA Typ.	7.0 mA Typ.	T use = +25 °C	o load, f <sub>0</sub> = 170 MHz	
Output disable	ourront	I dis	3.4 mA Max.	3.4 mA Max.	3.5 mA Max.	3.7 mA Max.	OE = GND, f <sub>O</sub> = 170 MHz		
Output disable (	current	I_uis	0.9 µA Max.	1.0 µA Max.	1.5 µA Max.	2.5 µA Max.	T use = +105 °C	<u> </u>	
Standby current	t	I_std		· · · · · · · · · · · · · · · · · · ·	0.5 µA Typ.		T_use = +105 °C T use = +25 °C	Ī = GND	
Cummatru		SYM	1 31 1 31 1			1.1 μA Typ.	T_use = +25 °C 50 % V <sub>CC</sub> Level		
Symmetry		STIVI	45 % ~ 55 %			I <sub>OH</sub> /I <sub>OL</sub> Conditions [mA]			
						Rise/Fall time			
		Vон	90 % V <sub>CC</sub> Min.				Default (f <sub>0</sub> > 40 MHz),	Іон -2.5 -3.5 -4.0 -5.0	
						Fast	l <sub>OL</sub> 2.5 3.5 4.0 5.0		
Output voltage							15 20 25 2		
(DC characteris	tics)		10 % V <sub>CC</sub> Max.				$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		
		.,							
		V <sub>OL</sub>							
							*C : 2.20 V ~ 2.80 V, *B : 1.98 V ~ 2.20 *C : 2.20 V ~ 2.80 V, *D : 2.70 V ~ 3.63		
Output load cor	ndition	L CMOS	15 pF Max.				O . 2.20 V	- 2.00 V, D . 2.70 V 3.00 V	
Output load col	idition	V <sub>IH</sub>	70 % V <sub>CC</sub> Min.						
Input voltage		VIII			/cc Max.		OE or ST		
		VIL							
	Default				ns Max.		f <sub>O</sub> > 40 MHz		
Rise and Fall		tr/tf	6.0 ns Max.			f <sub>O</sub> ≤ 40 MHz 20 % - 80 % V <sub>CC</sub>			
time	Fast			3.0	ns Max.		$f_0 = 0.67 \text{ MHz} \sim 170 \text{ MHz}$	L_CMOS = 15 pF	
Slow			10.0 ns Max.				f <sub>O</sub> = 0.67 MHz ~ 20 MHz		
Disable Time		t_stp	1 µs Max.			Measured from the time OE or $\overline{\text{ST}}$ pin crosses 30 % $V_{\text{CC}}$			
Enable Time		t_sta	1 µs Max.				Measured from the time OE pin crosses 70 % V <sub>CC</sub>		
Resume Time		t_res		3	ms Max.		Measured from the time ST pin crosses 70 % V <sub>CC</sub>		
Start-up time		t_str	3 ms Max.			Measured from the time V <sub>CC</sub> reaches its rated minimum value, 1.62 V			

<sup>\*1</sup> Frequency tolerance includes initial frequency tolerance, temperature variation, supply voltage variation, reflow drift, load drift and aging (+25 °C, 1 year).

## Spread spectrum configuration

	C: Center spread	⑤Code	02	05	07	10	15	20
	modulation	Spread percentage	±0.25 %	±0.5 %	±0.75 %	±1.0 %	±1.5 %	±2.0 %
4)	D: Down spread	⑤Code	05	10	15	20	30	40
	modulation	Spread percentage	-0.5 %	-1.0 %	-1.5 %	-2.0 %	-3.0 %	-4.0 %

Modulation frequency: 25.4 kHz (default), 6.3 kHz, 8.5 kHz, 12.7 kHz

Modulation profile: Hershey-kiss (default), Sine-wave, Triangle

### Product Name

SG-9101CG 170.000000MHz C 20 P H A A A 2 Package Type

(1) (2)

(3)

4567890

②Package Type
CA: 7.0 mm x 5.0 mm
CB: 5.0 mm x 3.2 mm

CE: 3.2 mm x 2.5 mm CG: 2.5 mm x 2.0 mm

©Function
P: Output enable
S: Standby

④Spread type

C: Center spread

D: Down spread

⑦Operating temperature
G: -40 °C ~ +85 °C
H: -40 °C ~ +105 °C

Modulation profileA: Hershey-kiss (default)B: Sine-waveC: Triangle

A: 25.4 kHz (default)		@Rise/Fall time
B: 12.7 kHz		A: Default
C: 8.5 kHz		B: Fast
D: 6.3 kHz	ı	C: Slow

①Model, ②Package type, ③Frequency,

 $<sup>\</sup>textcircled{4} \textbf{Spread type, } \textcircled{5} \textbf{Spread percentage code,} \\$ 

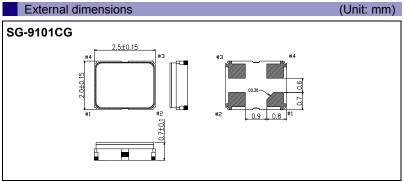
<sup>6</sup> Function, 7 Operating temperature,

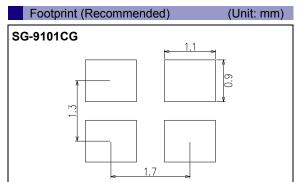
<sup>®</sup> Modulation frequency, 9 Modulation profile, 1 Rise/Fall time

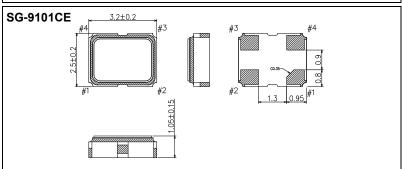


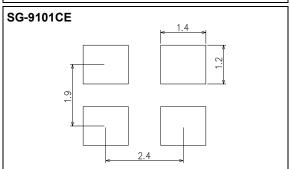
# Pin description

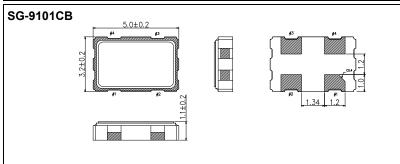
Pin	Name	I/O type		Function							
	OE Input		Output enable	High: Specified frequency output from OUT pin							
			Output eriable	Low: Out pin is low (weak pull down), only output driver is disabled.							
1						High: Specified frequency output from OUT pin					
	ST	Input	Standby	Low: Out pin is low (weak pull down),							
				Device goes to standby mode. Supply current reduces to the least as I_std.							
2	GND	Power	Ground								
3	OUT	Output	Clock output								
4	V <sub>CC</sub>	Power	Power supply								

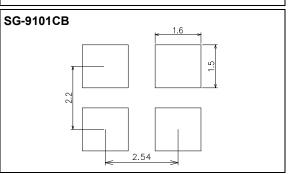


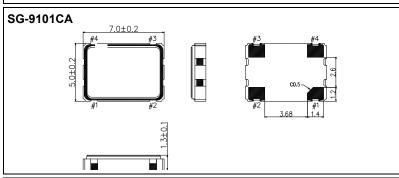


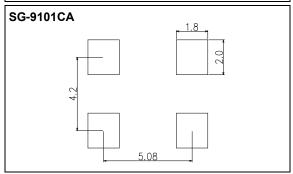








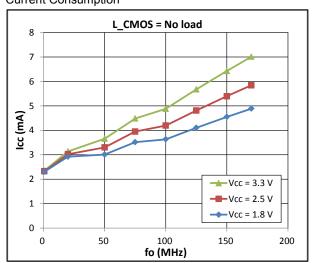


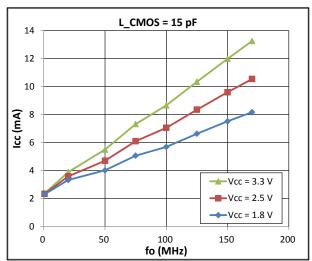


## ■Notes:

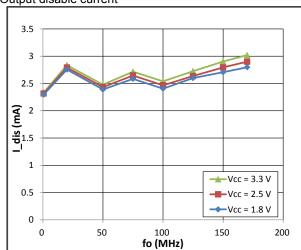
In order to achieve optimum jitter performance, the 0.1  $\mu$ F capacitor between  $V_{CC}$  and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

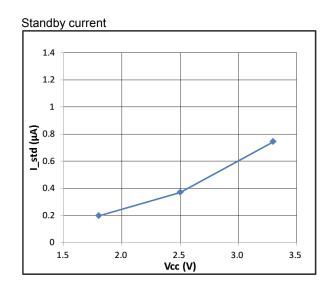
# Specification Graph (Typical supplemental specification. Unless otherwise specified T\_use = 25 °C, L\_CMOS = 15pF) Current Consumption





Output disable current



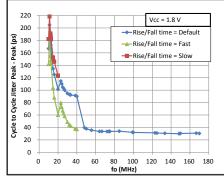


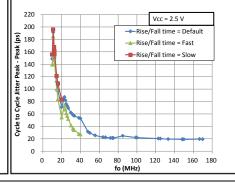
### ■Notes:

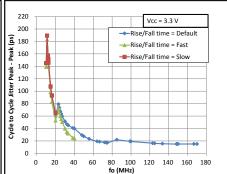
Spead percentage :  $\pm 2.0 \%$  , Modulation frequency : 25.4 kHz , Modulation profile : Hershey-kiss

# Specification Graph (Typical supplemental specification. Unless otherwise specified T\_use = 25 °C, L\_CMOS = 15pF)

Cycle-to-Cycle Jitter Peak-Peak





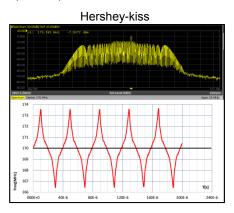


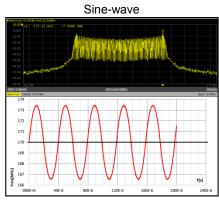
### ■ Notes:

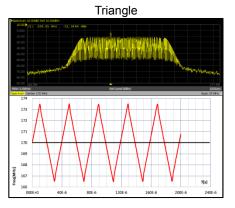
Spead percentage: ±2.0 %, Modulation frequency: 25.4 kHz, Modulation profile: Hershey-kiss

# Spread Spectrum Specification Graph

Spread Spectrum Profile fo: 170 MHz / Spread spectrum:  $\pm 2.0$  % / Modulation frequency: 25.4 kHz



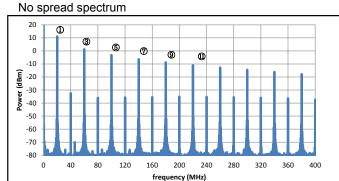




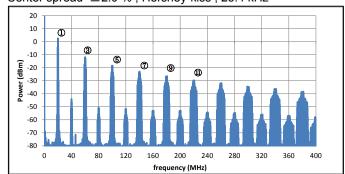
# Harmonics Specification Graph

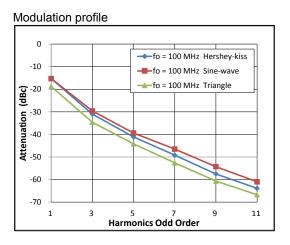
(Typical supplemental specification. Unless otherwise specified T\_use = 25 °C, L\_CMOS = 15pF, Vcc = 3.3 V)

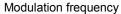
Harmonics spectrum (fo = 20 MHz)

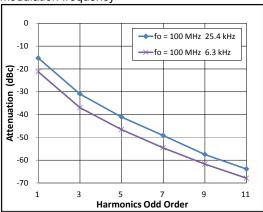


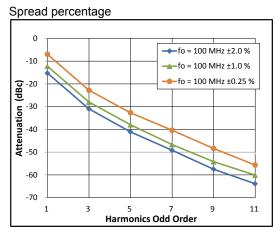
Center spread ±2.0 %, Hershey-kiss, 25.4 kHz



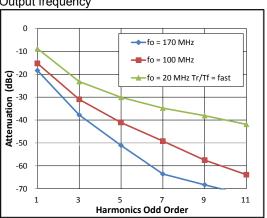








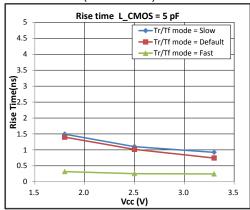


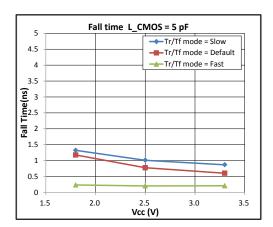


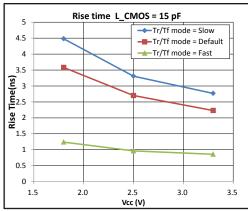
Hermonics order attenuation is normalizing to no-spread spectrum mode.

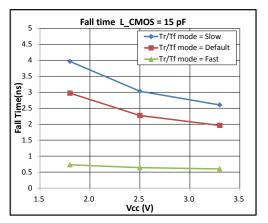
# Specification Graph (Typical supplemental specification. Unless otherwise specified T\_use = 25 °C, L\_CMOS = 15pF)

Rise/Fall Time (fo = 20 MHz)



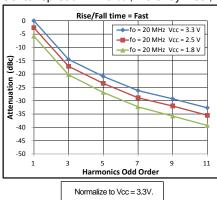


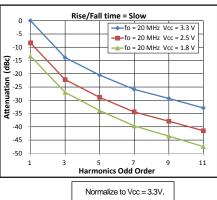


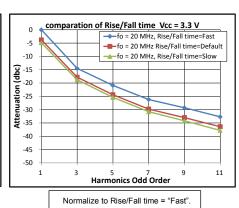


Harmonics comparison

Center spread ±2.0 %, Hershey-kiss, 25.4 kHz







# ■Notes:

frequency	uency slow		fast	
0.67 M – 20 M	See Slow	See Default	See Fast	
20 M – 40 M	-	See Default	See Fast	
40 M – 170 M	-	See Fast	See Fast	



# Simulation Model

IBIS Model is available upon request. Please contact us.
 Information Required: Oscillator operating condition (i.e. Power Supply, Rise/Fall Time, Temperature)

# ESD Rating

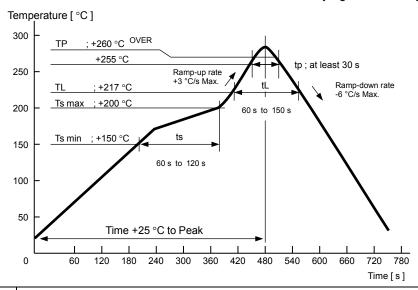
Test items	Breakdown voltage
Human Body Model (HBM)	2000V
Machine Model (MM)	250V
Charged Device Model (CDM)	750V

## Device Material & Environmental Information

Model	Package	# of	Reference	Terminal	Terminal	Complies	Pb	MSL	Peak
	Dimensions	Pins	Weight	Material	Plating	With EU	Free	Rating	Temp.
			(Typ.)			RoHS			(Max)
SG-9101CG	2.5x2.0x0.7mm	4	13 mg	W	Au	Yes	Yes	1	260°C
SG-9101CE	3.2x2.5x1.0mm	4	25 mg	W	Au	Yes	Yes	1	260°C
SG-9101CB	5.0x3.2x1.1mm	4	51 mg	W	Au	Yes	Yes	1	260°C
SG-9101CA	7.0x5.0x1.3mm	4	143 mg	W	Au	Yes	Yes	1	260°C

SMD products Reflow profile(example)

The availability of the heat resistance for reflow conditions of JEDEC-STD-020D.01 is judged individually. Please inquire.





• Pb free.



- Complies with EU RoHS directive.
  - About the products without the Pb-free mark.
     Contains Pb in products exempted by EU RoHS directive.
     (Contains Pb in sealing glass, high melting temperature type solder or other.)

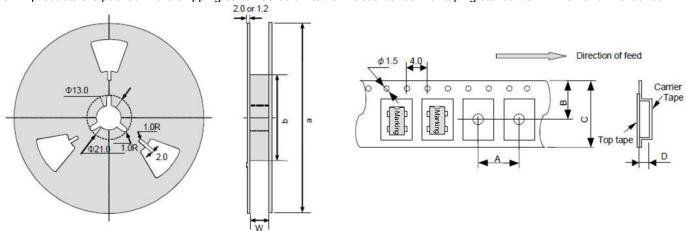


# Device Marking

Model	Factory Programmed Part Marking	Field Programmable Part Marking (Blank Samples)
SG-9101CG	Frequency Product code 170.S1 OA23DK  1pin mark Lot No.	Product code S1 OA23DK  1pin mark  Lot No.
SG-9101CE	Product code  170.0S1  o A23DK  1pin mark  Lot No.	Product code  S1  o A23DK  Lot No.
SG-9101CB	Frequency 170.0S1  O A23DK  Lot No.	S1  A23DK  A21 Din mark  Lot No.
SG-9101CA	Frequency 170.00S1  O A23DK  Lot No.	S1  o A23DK  Lot No.

# Standard Packing Specification

SMD products are packed in the shipping carton as below table in accordance with taping standards EIA-481 and IEC-60286



# Standard Packing Quantity & Dimension(Unit mm)

otaliana i aoimig adminity of 2 monoton (Cime i i i i )									
	Quantity	Reel Dimension			Care	Direction of			
Model	(pcs/Reel)	2	h	W	Δ Β	D	ВС	D	Feed (L= Left
	(pcs/keei)	а	D	VV	А	Ь		D	Direction)
SG-9101CG	3000	Ф180	Ф60	9	4	5.25	8	1.15	L
SG-9101CE	2000	Ф180	Ф60	9	4	5.25	8	1.4	L
SG-9101CB	1000	Ф180	Ф60	13	8	7.25	12	1.4	L
SG-9101CA	1000	Ф254	Ф100	17.5	8	9.25	16	2.3	L

# PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

### **WORKING FOR HIGH QUALITY**

In order provide high quality and reliable products and services than meet customer needs,

Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired ISO/TS 16949 certification that is requested strongly by major automotive manufacturers as standard.

ISO/TS16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

# Explanation of the mark that are using it for the catalog



►Pb free.



- ► Complies with EU RoHS directive.
  - \*About the products without the Pb-free mark.

    Contains Pb in products exempted by EU RoHS directive.

    (Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc.



▶ Designed for automotive applications related to driving safety (Engine Control Unit, Air Bag, ESC etc.).

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